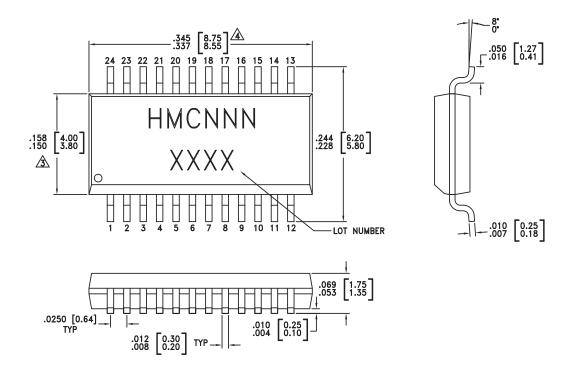


QS24 (E) – 24 LEAD PLASTIC QSOP PACKAGE



QS24 (E) Package Outline Drawing



NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
QS24	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HMCNNN XXXX
QS24E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HMCNNN XXXX

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX
- [4] 3-Digit part number NNN

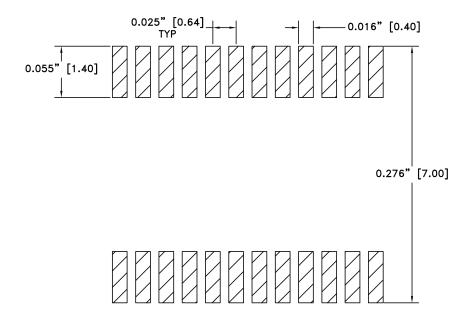


QS24 (E) – 24 LEAD PLASTIC QSOP PACKAGE



Suggested QS24 (E) PCB Land Pattern





NOTES:

- 1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.